

TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

ETAS ID: TM767703

SUBMISSION TYPE:	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:	RELEASE OF SECURITY INTEREST		
CONVEYING PARTY DATA			
Name	Formerly	Execution Date	Entity Type
SILICON VALLEY BANK		11/14/2022	Corporation: CALIFORNIA
RECEIVING PARTY DATA			
Name:	MOVELLA INC.		
Street Address:	2750 N. 1st St., Ste 300		
City:	San Jose		
State/Country:	CALIFORNIA		
Postal Code:	95131		
Entity Type:	Corporation: DELAWARE		
PROPERTY NUMBERS Total: 3			
Property Type	Number	Word Mark	
Serial Number:	90663667	MOVELLA	
Registration Number:	4732410	IGYRO	
Registration Number:	4732409	IGYRO	
CORRESPONDENCE DATA			
Fax Number:			
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>			
Phone:	4159831234		
Email:	sdipdocket@pillsburylaw.com		
Correspondent Name:	Sam E. Iverson		
Address Line 1:	Four Embarcadero Center, 22nd Floor		
Address Line 4:	San Francisco, CALIFORNIA 94111-5998		
NAME OF SUBMITTER:	Sam E. Iverson		
SIGNATURE:	/Sam E. Iverson/		
DATE SIGNED:	11/14/2022		
Total Attachments: 13			
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**RELEASE OF ADDENDUM TO INTELLECTUAL
PROPERTY SECURITY AGREEMENT**

THIS RELEASE OF ADDENDUM TO INTELLECTUAL PROPERTY SECURITY AGREEMENT (this “**Release**”) is made as of November 14, 2022, between MOVELLA INC., a Delaware corporation (formerly known as MCUBE, INC.) with its principal office at 2570 N. 1st St., Ste 300, San Jose, CA 95131 (“**Grantor**”), and SILICON VALLEY BANK, a California corporation, with its principal office located at 3003 Tasman Drive, Santa Clara, California 95054 (the “**Bank**”).

RECITALS

WHEREAS, in connection with certain loan documents, Bank and Grantor, and the other borrowers party thereto, entered into that certain Amended and Restated Loan and Security Agreement dated as of August 10, 2018 (as amended, supplemented, or otherwise modified from time to time, the “**Loan Agreement**”) and that certain Second Amendment to Amended and Restated Loan and Security Agreement dated as of June 8, 2020, by and between Bank and Grantor, and the other borrowers party thereto, (the “**Second Amendment**”);

WHEREAS, pursuant to and in conjunction with the Second Amendment and the Loan Agreement, Grantor executed and delivered to the Bank an Intellectual Property Security Agreement dated as of June 8, 2020 (the “**IP Agreement**”);

WHEREAS, pursuant to and in conjunction with the Second Amendment and the Loan Agreement, Grantor executed and delivered to the Bank an Addendum to Intellectual Property Security Agreement dated as of February 25, 2022 (the “**Addendum**”), which Addendum was recorded with the United States Patent and Trademark Office (“**USPTO**”) on March 2, 2022, in Reel 7647, Frame 0340, and Reel 59147, Frame 0471 for the purpose of securing certain obligations of Grantor to Bank;

WHEREAS, pursuant to and in conjunction with the Second Amendment and the Loan Agreement, and Addendum, Grantor granted Bank, for the benefit of Bank, a security interest in all of Grantor’s right, title and interest in and to the Intellectual Property Collateral (as defined in the IP Agreement)], including, without limitation, the Copyrights identified on Exhibit A attached hereto, Patents identified on Exhibit B attached hereto and the Trademarks identified on Exhibit C attached hereto (collectively, the “**Released Intellectual Property**”), and pledged and mortgaged (but did not transfer title to) such Intellectual Property to Bank; and

WHEREAS, the Bank acknowledges and agrees that the Loan Agreement and Second Amendment have been terminated or expired and has agreed to terminate, cancel, discharge and release all of its rights in the Released Intellectual Property secured by the Loan Agreement, the Second Amendment, and the Addendum, including, without limitation, reconveyance of any and all of the rights and interests of Bank that were pledged and mortgaged (but without the transfer of title) in and to the Released Intellectual Property to Grantor.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, and intending to be legally bound, and pursuant to the terms and conditions set forth in this Release, Grantor hereby agrees as follows:

1. DEFINED TERMS. All capitalized terms used but not otherwise defined herein have the meanings given to them in the Loan Agreement, Second Amendment and IP Agreement or Addendum.

2. TERMINATION AND RELEASE OF GRANT OF SECURITY INTEREST IN INTELLECTUAL PROPERTY COLLATERAL. Effective as of the date set forth above, Bank hereby terminates and releases in its entirety all security interests in the Released Intellectual Property, including the lien and security interest, granted pursuant to the Addendum, and Bank hereby assigns, reconveys and transfers to Grantor, without any representation, warranty, or recourse whatsoever, Bank's entire right, title, claim and interest in and to the Released Intellectual Property.

3. RECORDATION. Bank hereby authorizes and requests the Commissioner for Patents, the Commissioner for Trademarks, and the Register of Copyrights and any other government officials of the United States to record this Release, as applicable.

4. FURTHER ASSURANCE. The Bank hereby agrees to, at the sole expense of Grantor, duly execute, acknowledge, procure and deliver any further documents, including, but not limited to, those documents necessary under Article 9 of the Uniform Commercial Code or other applicable law, and to do such other acts as may be reasonable necessary to effect the release of the lien and security interest in the Released Intellectual Property contemplated hereby.

5. MODIFICATION. This Release may not be modified, nor may any provision hereof be waived, orally or in any manner other than by an agreement in writing signed by the parties hereto or their respective successors and assigns.

6. GOVERNING LAW. This Release and any claim, controversy, dispute or cause of action (whether in contract or tort or otherwise) based upon, arising out of or relating to this Release and the transactions contemplated hereby and thereby shall be governed by, and construed in accordance with, the laws of the United States and the State of California, without giving effect to any choice or conflict of law provision or rule (whether of the State of California or any other jurisdiction).

7. EXECUTION. Delivery of an executed signature page to this Release by facsimile or electronic transmissions (including .pdf file or Docu sign) shall be effective as delivery of an original signature.

(Signature follows on next page)

IN WITNESS WHEREOF, the Bank has caused this Release to be duly executed and delivered by its duly authorized office as of the date first written above.

SILICON VALLEY BANK, as Bank

By: DocuSigned by: Nina Davies
Name: Nina Davies
Title: Vice President

EXHIBIT A

Copyrights

Description	Registration Number	Application Number
None Identified		

EXHIBIT B

Patents

No.	Description	Registration/Application Number	Registration/Application Date
1.	Multi-Axis MEMS Rate Sensor Device	10,036,635	7/31/2018
2.	MEMS Structure with Improved Shielding and Method	10,046,964	08/14/2018
3.	Integrated Inertial Sensing Device	10,107,625	10/23/2018
4.	Multi-Axis Integrated MEMS Inertial Sensing Device on Single Packaged Chip	10,132,630	11/20/2018
5.	Method to Package Multiple MEMS Sensors and Actuators at Different Gases and Cavity Pressures	10,183,860	01/22/2019
6.	Centrifuge MEMS Stiction Test System and Method	10,317,333	06/11/2019
7.	Integrated MEMS Inertial Sensing Device	10,393,526	08/27/2019

No.	Description	Registration/Application Number	Registration/Application Date
8.	Transducer Structure and Method for MEMS Devices	8,477,473	07/02/2013
9.	Method and Structure of an Integrated MEMS Inertial Sensor Device Using Electrostatic Quadrature- Cancellation	9,075,079	07/07/2015
10.	Integrated Inertial Sensing Device	9,612,119	04/04/2017
11.	Wafer Level Centrifuge for MEMS Stiction Detection and Screening System and Method	9,651,473	05/16/2017
12.	Centrifuge MEMS Stiction Detection and Screening System and Method	9,758,374	09/12/2017
13.	MEMS Structure with Improved Shielding and Method	9,950,921	04/24/2018
14.	Apparatus and Methods for Integrated MEMS Devices	10,046,966	08/14/2018

No.	Description	Registration/Application Number	Registration/Application Date
15.	Method to Test the Quality Factor of a MEMS Gyroscope at Chip Probe	10,267,636	04/23/2019
16.	Apparatus and Methods for Integrated MEMS Devices	10,479,676	11/19/2019
17.	Ultra-Low Power Sensor for Vibration & Motion Detection	10,982,944	04/20/2021
18.	Method and Structure of an Inertial Sensor Using Tilt Conversion	8,869,616	10/28/2014
19.	Method and Device of MEMS Process Control Monitoring and Packaged MEMS with Different Cavity Pressures	9,249,012	02/02/2016
20.	Methods and Structures of Integrated MEMS-CMOS Devices	9,276,080	03/01/2016
21.	Synchronous Modulation Resonator with Sigma Delta Modulator	9,379,733	06/28/2016

No.	Description	Registration/Application Number	Registration/Application Date
22.	Integrated MEMS Inertial Sensing Device with Automatic Gain Control	9,513,122	12/06/2016
23.	Multi-Axis Integrated Inertial Sensing Device	9,541,396	01/10/2017
24.	Method to Package Multiple MEMS Sensors and Actuators at Different Gases and Cavity Pressures	9,725,304	08/08/2017
25.	Methods and Structures of Integrated MEMS-CMOS Devices	9,950,924	04/24/2018
26.	Multiple MEMS Device and Methods	PCT US2017019766	02/27/2017
27.	Apparatus and Methods for Integrated MEMS Devices	PCT US2017025992	04/04/2017
28.	Transducer Structure and Method for MEMS Devices	9,377,487	06/28/2016
29.	Methods and Apparatus for Mobile	15/368,514	12/02/2016

No.	Description	Registration/Application <u>Number</u>	Registration/Application <u>Date</u>
	Device Event Detection		
30.	Method and Device of MEMS Process Control Monitoring and Packaged MEMS with Different Cavity Pressures	10,343,896	07/09/2019
31.	Apparatus and Method for Integrated MEMS Devices (China)	201780034773.3	04/04/2017
32.	Methods and Structures of Integrated MEMS- CMOS Devices (China)	CN106698330	03/29/2019
33.	Power Saving Method of Operating Portable Computing Device (China)	201410374656.X	07/31/2014
34.	Method and Structure of an Integrated MEMS Inertial Sensor Devices Using Electrostatic Quadrature- Cancellation (EP)	14171673	06/09/2014
35.	Multi-Axis Integrated MEMS	2759802	01/02/2019

No.	Description	Registration/Application <u>Number</u>	Registration/Application <u>Date</u>
	Inertial Sensing Device on Single Packaged Chip (EP)		
36.	System on a Chip Using Integrated MEMS and CMOS Devices (China)	CN202717577	02/06/2013
37.	Dynamic Offset Calibration (China)	CN103246366	11/14/2017
38.	Methods and Structures of Integrated MEMS-CMOS Devices (China)	CN103303859	01/18/2017
39.	Methods and Structures of Integrated MEMS-CMOS Devices (Taiwan)	TWI525792	03/11/2016
40.	Methods and Structures of Integrated MEMS-CMOS Devices (Taiwan)	TWI601268	10/01/2017
41.	Methods and Structures of Integrated MEMS-CMOS Devices (Taiwan)	TWI654738	03/21/2019

No.	Description	Registration/Application Number	Registration/Application Date
42.	Integrated Inertial Sensing Device and System Including the Same (Taiwan)	TWI506246	11/01/2015
43.	Multi-Axis MEMS Rate Sensor Device (Taiwan)	TWI606229	11/21/2017
	Multi-Axis MEMS Inertial Sensing Device on Single Packaged Chip (Taiwan)	TWI518302	01/21/2016
44.	Centrifuge MEMS Stiction Detection and Screening System and Method (China)	201410117025	
45.	MEMS-Based Proximity Sensor Device and Method (Taiwan)	TWI509502	11/21/2015
46.	MEMS-Based Proximity Sensor Device and Method (China)	CN104219346	12/01/2017
47.	A MEMS Structure with Improved Shielding and Method (Taiwan)	TWI579229	04/21/2017

No.	Description	Registration/Application <u>Number</u>	Registration/Application <u>Date</u>
48.	Method and Structure of Monolithically Integrated Absolute Pressure Sensor (Taiwan)	TWI528566	04/01/2016

EXHIBIT C

Trademarks

No.	Description	Registration/Serial Number	Registration/ Application Date
1.	MOVELLA	90/663,667	04/22/2021
2.	IGYRO	4,732,410	05/05/2015
3.	IGYRO	4,732,409	05/05/2015
4.	MOVELLA (Canada)	2139715	04/27/2021
5.	MOVELLA (International)	1618617	04/27/2021
6.	SENSFIT (United Kingdom)	918173087	06/16/2020
7.	SENSFIT (EU)	018173087	06/18/2020
8.	MOVELLA (Australia)	2218566	04/27/2021
9.	VGYRO (China)	12780832	10/28/2014
10.	MOVELLA (Taiwan)	110033208	05/11/2021